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(54) **POLYAMIDE MOLDING**

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(57) **PURPOSE:** To obtain a polyamide molding which has excellent gas-barrier properties without detriment to the excellent toughness inherent in a polyamide resin.

**CONSTITUTION:** This molding is produced from a compsn. comprising a polyamide resin and a layered silicate microdispersed therein, and the molding satisfies the relations:  $0.05 \leq A \leq 5$ ,  $P \leq kA + N$ , and  $k = 0.0017N^2 - 0.43N + 0.14$  [wherein A is the ash content (wt.%) of the molding; P is the oxygen permeability (cc/day/m<sup>2</sup>/atm) per 25μm-thickness of the molding at 23°C under a relative humidity of 95%; and N is the value of P when A is 0].